

IN THE SPECIFICATION:

Please amend paragraph number [0043] as follows:

[0043] FIG. 17B is a side view of another exemplary semiconductor die formed in accordance with the invention, illustrating a balancing of tensile stress; ~~and~~

Please amend paragraph number [0044] as follows:

[0044] FIG. 18 is a view of the back side of exemplary portions of a semiconductor wafer to which three forms of a stress-balancing layer are applied in accordance with the invention; and [[.]]

Please enter new paragraph number [0044a] as follows:

[0044a] FIG. 19 is a simplified schematic view of a conventional laser marking system.